

Amendments to the Claims

Please cancel claims 23 – 31 and 37 - 42 and add claims 43 – 57, as indicated herein.
This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. – 42. (Cancelled)

43. (New) An actuation assembly comprising:

- a gimbal;
- a slider;
- a slider bond pad for electrically connecting the slider to the gimbal, the slider bond pad having at least two layers;
- a ball bond for connecting the slider bond pad to the gimbal;
- a notch located below the slider bond pad and on an edge of the slider, wherein the edge is adjacent the gimbal; and
- wherein the notch and the slider bond pad provide compensation for potential misalignment between the slider and the gimbal.

44. (New) The actuation assembly according to claim 43, wherein the notch has a height with respect to the gimbal of about 25 microns.

45. (New) The actuation assembly according to claim 43, wherein the slider bond pad has a thickness of about 15 microns.

46. (New) The actuation assembly according to claim 43, wherein the slider bond pad has a thickness of about 5 microns.

47. (New) An actuation assembly comprising:

- a gimbal that includes a flex on suspension bond pad;

a slider body, wherein the slider body comprises a front side;
a slider bond pad extending from the front side for electrically connecting to the flex on suspension bond pad, the slider bond pad having a pad extension adjacent to the front side and a pad adjacent the pad extension;
a ball bond for electrically connecting the pad to the flex on suspension bond pad;
a notch located along the front side;
wherein the notch and the slider bond pad provide compensation for potential misalignment between the slider and the gimbal.

48. (New) The actuation assembly according to claim 47, wherein the pad extension comprises nickel iron.

49. (New) The actuation assembly according to claim 48, wherein the pad comprises gold.

50. (New) The actuation assembly according to claim 49, further comprising a load beam connected to the gimbal

51. (New) The slider according to claim 49, wherein the slider bond pad has a thickness of about 15 microns.

52. (New) An actuation assembly comprising:

a slider;
a gimbal;
a bond pad for electrically connecting the slider to the gimbal, the bond pad having at least two layers;
a ball bond for connecting the bond pad to the gimbal;
an indentation along an edge of the slider, wherein the indentation is proximate the bond pad and is positioned between the bond pad and the gimbal; and

wherein the indentation and the bond pad provide compensation for potential misalignment between the bond pad and the holding member.

53. (New) The device according to claim 52, wherein the at least two layers comprises a first layer and a second layer;

the first layer is proximate the slider and the second layer is proximate the first layer; and
the first layer comprises nickel iron.

54. (New) The device according to claim 53, wherein the second layer comprises gold.

55. (New) The device according to 52, wherein the indentation has a height with respect to the gimbal of about 25 microns.

56. (New) The device according to claim 52, wherein the bond pad has a thickness of about 5 microns.

57. (New) The device according to claim 52, wherein the bond pad has a thickness of about 15 microns.